

FEATURES

- Specially customized for use in game consoles and controllers
- High degree of inrush current capability
- Precise melting time
- Surface mount technology allows fuses to be directly attached to printed circuit boards
- Notebook Computer Wireless Base Station Networking Telecom System
- Significant savings in weight and real estate
- RoHS / REACH

RS PRO, Fuse, Ceramic SMD LTCC Chip Fuse, Slow Blow, 2A-8A 63V, 0603

RS Stock No.: 2522139 2522140



RS Professionally Approved Products bring to you professional quality parts across all product categories. Our product range has been tested by engineers and provides a comparable quality to the leading brands without paying a premium price.

Surface Mount Fuse — LTCC Chip Fuse



Product Description

Ceramic SMD LTCC Chip Fuse, Slow Blow, 2A-8A 63V, 0603

Applications:

- Notebook Computer
- Wireless Base Station
- Networking
- Telecom System

General Specifications

-	
Current Rating	2A, 2.5A, 3A, 4A, 5A, 6A 8A
Voltage Rating	63V
Body Material	Ceramic
Operating Temperature	-55°C to +125°C
Country of Origin	Taiwan

Electrical Characteristics

		Opening Time			
Rated Current	1 In	2 In		3 In	10 In
current	Min.	Min.	Max.	Max.	Max.
2A-8A	4 hr	1 sec	120 sec	3 sec	0.05 sec

Surface Mount Fuse — LTCC Chip Fuse

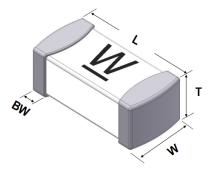


I²t Nominal Cold Resistance & I²t &Safety Approval:

Approvals	Marking	Interrupting rating	c AS us	Nominal Cold Resistance (Ohms)	Nominal Melting I ² t (A ² sec.)
2A	<u>N</u>	60A @ 32V DC 35A @ 63V DC	*	0.0364-0.0676	0.400
2.5A	<u>0</u>		*	0.0280-0.0520	0.625
3A	<u>P</u>		*	0.0182-0.0338	1.170
4A	<u>s</u>		*	0.0105-0.0195	2.210
5A	Ţ		*	0.0070-0.0130	2.500
6A	<u>U</u>		*	0.0049-0.0091	5.040
8A	w		*	0.0035-0.0065	7.680

Shape & Dimension:

Туре	0603
L	1.6 ± 0.2 mm
W	0.8 ± 0.2 mm
Т	0.8 ± 0.2 mm
BW	0.36 ± 0.15 mm



Recommended Pad Layout		
L1	0.66 mm	
L2	0.76 mm	
w	1.00 mm	

